

Ultrasonic Phased Array Inspection of Composites Course Outline

1.0 Introduction and course objectives

- 1.1 Brief history of phased array
- 1.2 Capabilities / advantages of phased array
- 1.3 Course objectives
- 1.4 Phased Array Inspector Certification requirements
- 1.5 Refresher of basic ultrasonic principles

2.0 Ultrasonic phased array digitization principles

- 2.1 Advantages of digital recording
- 2.2 Digital amplitude
- 2.3 Sampling rate
- 2.4 Time for one wavelength
- 2.5 Minimum sampling requirements
- 2.6 Ideal sampling requirements
- 2.7 Pulse shape
- 2.8 Pulse duration principles for signal optimization
- 2.9 Signal averaging
- 2.10 Element excitation
- 2.11 Number of A scans needed to create an S-scan
- 2.12 PRF / Scan speed relationship
- 2.13 Effect of averaging on scan speed
- 2.14 PRF issues
- 2.15 Probe frequency spectrum
- 2.16 Bandwidth
- 2.17 Bandpass filters
- 2.18 Video smoothing filters
- 2.19 Gray scale palette
- 2.20 Color scale palette
- 2.21 Swept angle imaging
- 2.22 Data collection rate
- 2.23 Display options - A scan - B scan - C scan - S scan

3.0 Introduction to phased array principles

- 3.1 What are phased arrays
- 3.2 Why use phased arrays
- 3.3 Phased array terminology
- 3.4 Probe parameters
- 3.5 Probe manufacturing, composite crystal technology
- 3.6 Phased array probe design
- 3.7 Wedge parameters
- 3.8 Comparison with conventional versus phased array wave forming technology
- 3.9 Beam forming using phased array principles
- 3.10 Transmitting delays
- 3.11 Receiving delays
- 3.12 Focal law generation
- 3.13 Focal law calculation
- 3.14 Beam focusing
- 3.15 Dynamic Depth Focusing (DDF)
- 3.16 Beam steering

- 3.17 Sectorial scanning
- 3.18 Element size effects on beam steering
- 3.19 Electronic scanning
- 3.20 Summary of scan types
- 3.21 Array selection
- 3.22 Frequency and aperture type
- 3.23 Element size summary
- 3.24 How many elements to use
- 3.25 Power of the elements
- 3.26 Design compromise
- 3.27 Choosing the pitch and aperture size
- 3.28 Array lobes

4.0 Instrument specific orientation and basic operating instructions

- 4.1 Available modules
- 4.2 Module specifications
- 4.3 Software screen
- 4.4 User interface options
- 4.5 Direct access buttons
- 4.6 Main menu
- 4.7 The menu structure
- 4.8 Using Gate / Alarms
- 4.9 Calibration Wizards
- 4.10 User options

5.0 Programming and process control procedures for the Equipment.

(Group practical session following Instructors presentation).

- 5.1 General user information
- 5.2 Basic connections and powering up
- 5.3 Probe / Part calibration
- 5.4 Focal Law calibration
- 5.5 UT settings calibration
- 5.6 Display selection
- 5.7 Probe array dead element check
- 5.8 Element sensitivity calibration procedure
- 5.9 Wedge delay calibration procedure
- 5.10 TCG (Time Corrected Gain) calibration procedure
- 5.11 Sound velocity calibration procedure
- 5.12 Encoder calibration procedure
- 5.13 Flaw sizing procedure
- 5.14 Creating a report
- 5.15 Storing the set up file
- 5.16 Creating a defect table

6.0 Composite Manufacturing Technology

- 6.1 Material Types - Composites, Plastics, GRP
- 6.2 Resin types
- 6.3 Fibre lay-up options
- 6.4 Resin application processes – Pre-preg, Brush applications, RTM/RTI
- 6.5 Pre-preg manufacturing
- 6.6 Lay-up and curing

- 6.7 Ply stacking and orientation
- 6.8 Autoclave cure cycle
- 6.9 Honeycomb core CFC
- 6.10 Co-curing
- 6.11 Co-bonding
- 6.12 Bonding
- 6.13 Product Forms
- 6.14 CFC honeycomb stiffened assemblies
- 6.15 Blade stiffened skins
- 6.16 Spar stiffened assemblies
- 6.17 Spar stiffened and honeycomb stiffened assemblies
- 6.18 Discontinuity / Flaw types
- 6.19 Definition of discontinuities and defects
- 6.20 Defect origins
- 6.21 Defect types and nature
- 6.22 Retained backing material
- 6.23 Porosity
- 6.24 Un-bonds
- 6.25 Honeycomb defects
- 6.26 Core splice
- 6.27 Distorted cells
- 6.28 Blistered cells
- 6.29 Blistered skins
- 6.30 Impact damage

7.0 Practical exercises

- 7.1 Practical exercises using pre-programmed set-up files
- 7.2 Process control checks:
- 7.3 Setting up the equipment for specific inspections per SB's, AD's and NTM requirements. (Impact damage detection and plotting, scarf patch inspection).
- 7.4 Performing scans.
- 7.5 Storing the set-up files.
- 7.6 Creating saving and analyzing data files
- 7.7 Defect sizing
- 7.8 Building and printing a report.
- 7.9 Developing new PA procedures for the OmniScan.

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